

**REMARKS**

Claims 6-10, 21-22 are pending in the application.

Claims 6-10, 21-22 are rejected under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent No. 5,070,297 of Kwon et al. ("Kwon")

Specifically, the Examiner states that:

As to claims 6-7, Kwon et al. disclose in Figs. 3, a testing device for testing a integrated circuit comprising: a probe (16 of figure 3) for transmitting and receiving the signal to the integrated circuit (42 of figure 3); and the probe connecting to the high-speed electrical component (46-72 of figure 3) for transmitting a high-speed electrical signal from the high-speed electrical component to the component (42 of figure 3); and identifying and evaluating a response by the component to the high-speed electrical signal (col. 1, lines 20-24, and col. 3, lines 25-35). Kwon et al. Do not disclose the device under test is a optical component. However, It would have been obvious to a person having ordinary skill in the art at the time the invention to recognize the integrated circuit including the optical component. (12/22/2006 Office Action, pp. 2-3)

Applicants respectfully submit that Kwon does not render Claims 6-10 and 21-22 unpatentable under 35 U.S.C. §103(a).

Kwon discloses a full wafer integrated circuit testing device that, in conjunction with a test control unit, tests integrated circuits formed as a wafer. Probe units on the testing are associated with respective integrated circuits. Probe tips on probe units communicate with respective pads of the integrated circuits. Interface circuitry within each probe unit selectively communicates test data between the test control unit and the integrated circuit that the probe unit tests. Test pins have positions on probe units associated with respective integrated circuit connection points for testing associated integrated circuit components. Interface circuitry can include comparators that compare signals between the integrated circuit and the test control unit. Memory components store data associated with signals from test control unit and said integrated circuit. (Kwon, col. 2, line 61 to col. 3, line 8)

Kwon does not teach or suggest connecting a high-frequency probe to a golden high-speed electrical component, transmitting a high-speed electrical signal from the golden high-speed electrical

component to the optical component, and identifying a response by the optical component. In fact, Kwon teaches away from this as Kwon discloses comparators that "receive expected output signals" which "represent the signals that a fully functional integrated circuit would send to signal repeaters 50 and 52, respectively". (Kwon, col. 5, line 64-68, underline emphasis added by the Applicants) The comparators compare these expected output signals to the actual signals from the signal repeaters to determine if the signals match, thus indicating a fully functional integrated circuit. (Kwon, col. 5, line 68 to col. 6, line 4) Therefore, the "expected output signals" used in the method disclosed by Kwon are merely representative of "signals that that a fully functional integrated circuit would send".

In contrast, Claim 6 is limited to:

6. A method for testing an optical component, comprising:
  - connecting the optical component to a high-frequency probe;
  - connecting the high-frequency probe to a golden high-speed electrical component;
  - transmitting a high-speed electrical signal from the golden high-speed electrical component to the optical component; and
  - identifying a response by the optical component to the high-speed electrical signal. (underline emphasis added by the Applicants)

Given that Claims 7-10, 21-22 directly or indirectly depend on Claim 6, Applicants submit that Kwon does not also render Claims 7-10, 21-22. In view of the arguments set forth herein, it is respectfully submitted that the applicable rejections have been overcome. Accordingly, it is respectfully submitted that Claims 7-10, 21-22 are in condition for allowance.

If there are any charges, please charge them to our Deposit Account No. 500-654.

Respectfully submitted,

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